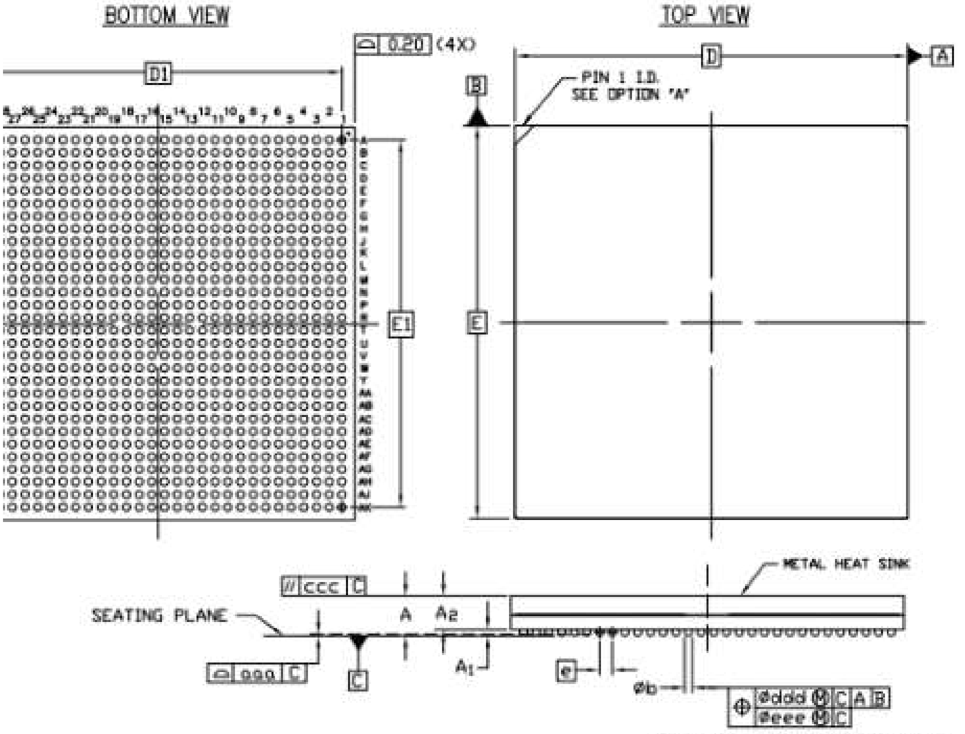

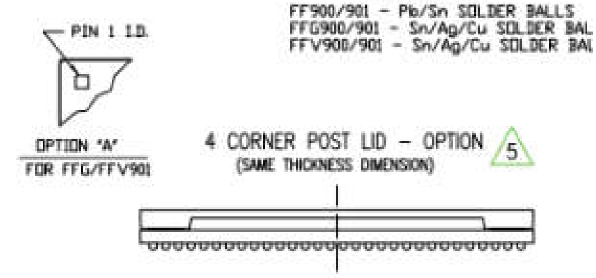

	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
	2.95	3.15	3.35	
1	0.40	0.50	0.60	
2	2.55	~	2.75	
E	31.00 BASIC			
E1	29.00 REF			
	1.00 BASIC			
	0.50	0.60	0.70	4
	~	~	0.20	
	~	~	0.35	
	~	~	0.30	
	~	~	0.10	
	30			2

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE
3. CONFORMS TO JEDEC MS-034-AAN-1
4. ACTUAL SOLDER BALL COUNT = 900
5. 4 CORNER POST LID IS USED FOR FFG/FFV901

ug475_c4_05_07

FF900, FFG900, FFV900, FF901, FFG901, and FFV901 Flip-Chip BGA Package Specif